



# Ai-M62-07S Specification

Version V2.0.0

Copyright ©2023

## Document resume

Version	Date	Develop/revise content	Edition	Approve
V2.0.0	2023.10.17	First Edition	Shengxin Zou	Ning Guan

## Content

1. Product overview .....	4
1.1 Characteristics .....	5
2. Main parameters .....	6
2.1. Electrostatic requirements .....	6
2.2. Electrical characteristics .....	7
2.3. Wi-Fi RF performance .....	7
2.4. BLE RF performance .....	8
2.5. Power consumption .....	8
3. Appearance size .....	9
4. Pin definition .....	10
5. Schematic diagram .....	12
6. Design guidance .....	13
6.1. Guidance of application circuit .....	13
6.2. Recommend PCB package size .....	13
6.3. Antenna layout requirements .....	14
6.4. Power supply .....	14
6.5. GPIO .....	14
7. Storage condition .....	15
8. Reflow welding curve diagram .....	16
9. Product packaging information .....	17
10. Contact us .....	17
Disclaimer and copyright notice .....	18
Notice .....	18
Important statement .....	19

# 1. Product overview

Ai-M62-07S is a Wi-Fi 6 + BLE5.3 module developed by Shenzhen Ai-Thinker Technology Co., Ltd. The module is equipped with BL616 chip as the core processor, supports Wi-Fi 802.11b/g/n/ax protocol and BLE protocol, and supports Thread protocol. The BL616 system includes a low-power 32-bit RISC-V CPU with floating-point unit, DSP unit, cache and memory, with a maximum dominant frequency of 320M.

Ai-M62-07S module has rich peripheral interfaces, including Audio Codec, USB2.0, SDU, SD / MMC (SDH), SPI, UART, I2C, I2S, PWM, GPDAC, GPADC, ACOMP and GPIO. It can be widely used in audio and video multimedia, Internet of Things (IoT), mobile devices, wearable electronic devices, smart home and other fields.

Ai-M62-07S module Sec Eng module supports AES / SHA / PKA / TRNG and other functions, supports mirror encryption and signature startup, to meet the needs of various security applications in the field of the Internet of Things.

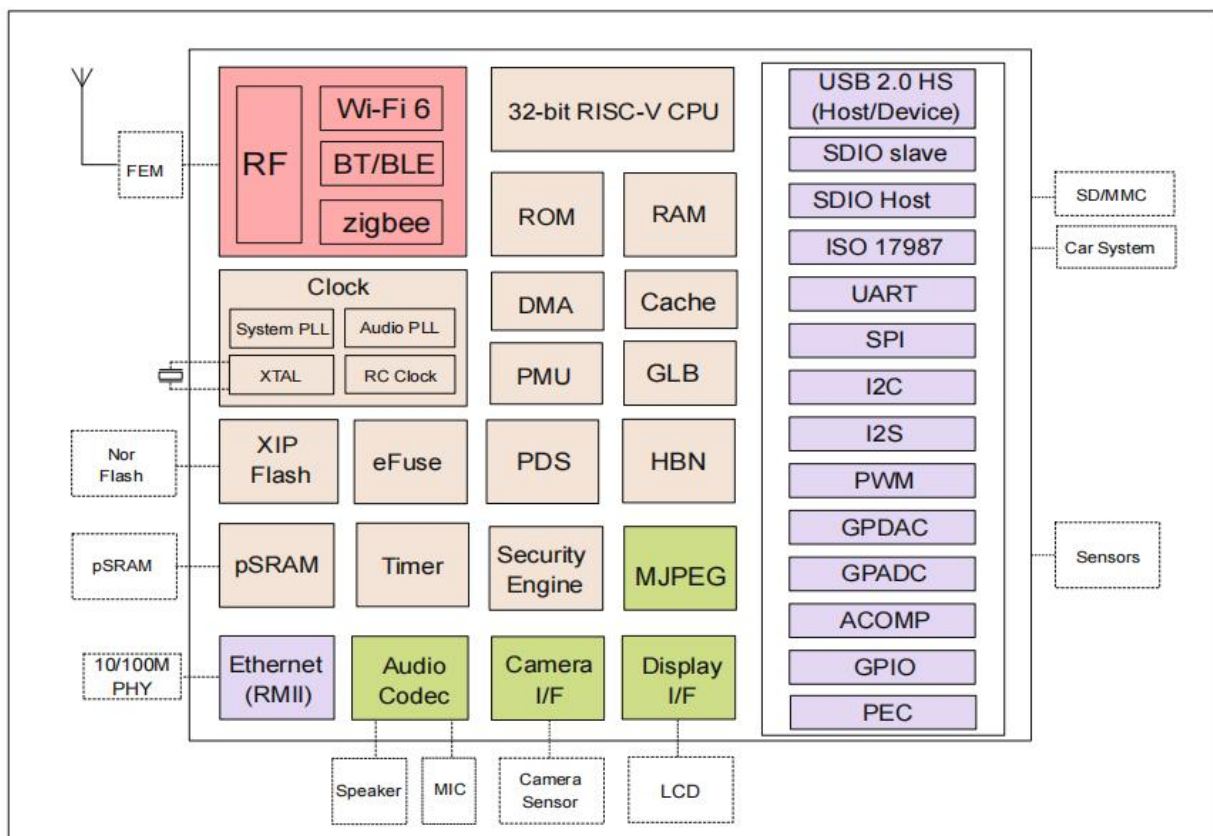


Figure 1 Main chip architecture diagram

## 1.1 Characteristics

- SMD-22 package
- Supports 2.4GHz operating frequency band
- Support IEEE 802.11 B/g/n/ax
- Support BLE5.3
- Support Thread
- Support Wi-Fi/BLE/Thread coexistence
- Wi-Fi security support WPS/WEP/WPA/WPA2/WPA3
- Supports 20/40MHz bandwidth, 1T1R, maximum rate 229.4 Mbps
- Support STA, SoftAP, STA + SoftAP and sniffer modes
- 32-bit RISC-V CPU with FPU and DSP, with a maximum dominant frequency of 320M
- 532KB SRAM, 128KB ROM, 4Kb eFuse
- Support USB2.0, SDU, SD/MMC(SDH), SPI, UART, I2C, I2S, PWM, GPDAC, GPDC, ACOMP, GPIO, etc.
- Integrated RF Balun, PA/LNA
- Support for safe startup and safe debugging
- Support XIP QSPI On-The-Fly AES decryption (OTFAD)
- Support TrustZone
- Support AES-CBC/CCM/GCM/XTS mode
- Support MD5, SHA-1/224/256/384/512
- TRNG (True Random Number Generator) is supported
- Support PKA (Public Key Accelerator) for RSA/ECC
- BLE-enabled Wi-Fi fast connection
- Universal AT command can be used quickly.
- Supports secondary development and integrates Windows and Linux development environments

## 2. Main parameters

**Table 1 Description of main parameters**

<b>Model</b>	Ai-M62-07S
<b>Package</b>	SMD-22
<b>Size</b>	17.0*16.0*3.1( $\pm 0.2$ )mm
<b>Antenna</b>	IPEX antenna
<b>Frequency</b>	2400 ~ 2483.5MHz
<b>Operating temperature</b>	-40℃~ 85℃
<b>Storage temperature</b>	-40℃~ 125℃, < 90%RH
<b>Power supply</b>	Power supply voltage 2.97V ~ 3.6V, power supply current $\geq 500$ mA
<b>Interface</b>	USB2.0, SDU, SD / MMC (SDH), SPI, UART, I2C, I2S, PWM, GPDAC, GPADC, ACOMP and GPIO, etc
<b>IO</b>	15
<b>UART rate</b>	Default 115200 bps
<b>Security</b>	WPS/WEP/WPA/WPA2/WPA3
<b>Flash</b>	Default 4MByte, max support 16MByte

### 2.1. Electrostatic requirements

Ai-M62-07S are electrostatic sensitive equipment, special precautions need to be taken when handling.



**Figure 2 ESD preventive measures**

## 2.2. Electrical characteristics

**Table 2 Electrical characteristics table**

Parameter	Condition	Min.value	Typical value	Max. value	Unit
Supply voltage	VDD	2.97	3.3	3.6	V
I/O	VIL	-	-	0.3*VDDIO	V
	VIH	-	0.7*VDDI	-	V
	VOL	-	-	0.1*VDDIO	V
	VOH	-	-	0.9*VDDIO	V
	IMAX	-	-	-	15

## 2.3. Wi-Fi RF performance

**Table 3 Wi-Fi RF Performance Table**

Description	Typical value			Unit
Frequency range	2400 ~ 2483.5MHz			MHz
<b>Output power</b>				
Mode	Min. value	Typical value	Max. value	Unit
11ax mode HE40, PA output power	-	16	-	dBm
11ax mode HE20, PA output power	-	17	-	dBm
11n mode HT40, PA output power	-	19	-	dBm
11n mode HT20, PA output power	-	19	-	dBm
11g mode, PA output power	-	19	-	dBm
11b mode, PA output power	-	22	-	dBm
<b>Receiving sensitivity</b>				
Mode	Min. value	Typical value	Max. value	Unit
11b, 1 Mbps	-	-98	-	dBm
11b, 11 Mbps	-	-90	-	dBm
11g, 6 Mbps	-	-93	-	dBm
11g, 54 Mbps	-	-76	-	dBm
11n, HT20 (MCS7)	-	-73	-	dBm
11ax, HE20 (MCS9)	-	-70	-	dBm
11ax, HE40 (MCS9)	-	-67	-	dBm

## 2.4. BLE RF performance

**Table 4 BLE RF performance table**

Description	Typical value			Unit
Frequency range	2400 ~ 2483.5MHz			MH
<b>Output power</b>				
Rate mode	Min.	Average	Max.	Unit
1Mbps	-	10	15	dBm
2Mbps	-	10	15	dBm
<b>Receiving sensitivity</b>				
Rate mode	Min.	Average	Max.	Unit
1Mbps sensitivity @30.8%PER	-	-99	-	dBm
2Mbps sensitivity @30.8%PER	-	-97	-	dBm

## 2.5. Power consumption

The following power consumption data are based on the 3.3V power supply and the ambient temperature of 25° C.

- The POUT power for all transmission modes is measured at the antenna interface.
- All emission data were measured based on a 100% duty cycle, in a continuous emission mode.

**Table 5 Power consumption table**

Mode	Min.	Average	Max.	Unit
Tx 802.11b, 11Mbps, POUT=+22dBm	-	394	-	mA
Tx 802.11g, 54Mbps, POUT =+19dBm	-	302	-	mA
Tx 802.11n, MCS7, POUT =+19dBm	-	302	-	mA
Tx 802.11ax, MCS9, POUT =+17dBm	-	269	-	mA
Rx 802.11b, packet length 1024 bytes	-	59	-	mA
Rx 802.11g, packet length 1024 bytes	-	59	-	mA
Rx 802.11n, packet length 1024 bytes	-	59	-	mA
Rx 802.11ax, packet length 1024 bytes	-	59	-	mA



### 3. Appearance size

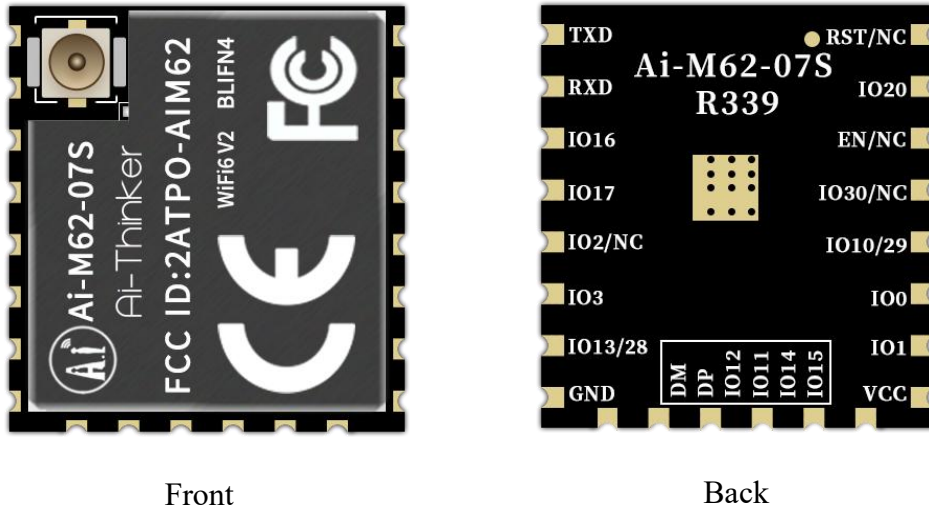


Figure 3 Appearance diagram (the picture is for reference only, subject to the physical object)

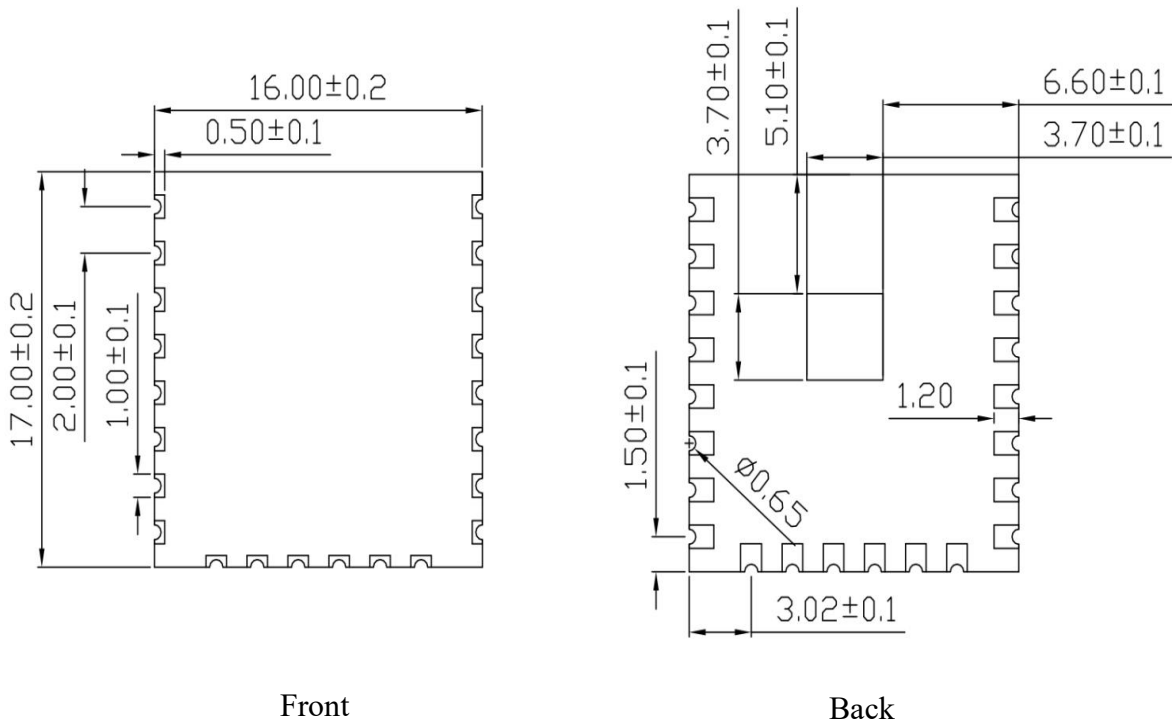
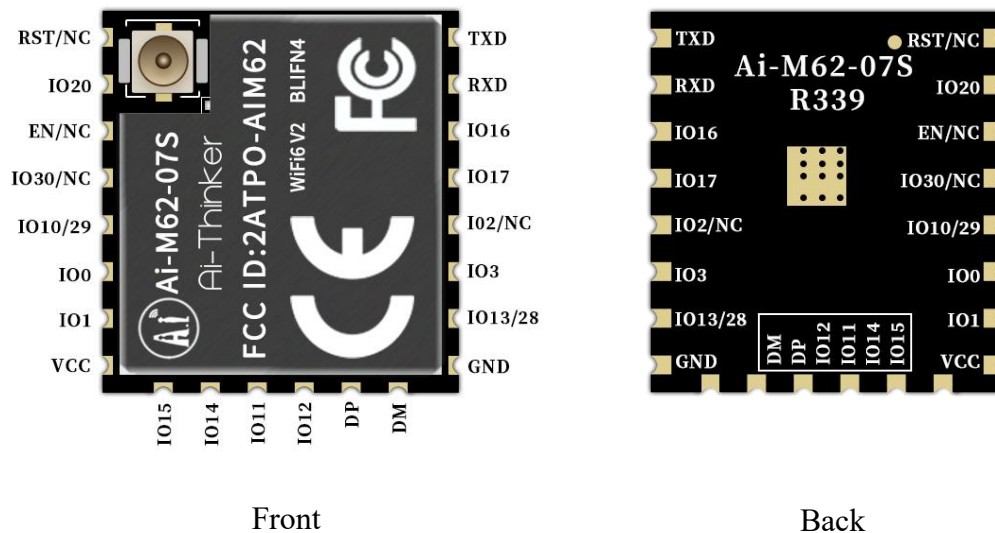


Figure 4 Size diagram

## 4. Pin definition

Ai-M62-07S module is connected to a total of 22 pins, refer to the schematic diagram of the pin, the pin function definition table is the interface definition.



**Figure 5 Schematic diagram of pin**  
**Table 6 Definitions of pin function**

No.	Name	Function
1	RST/NC	Default NC, can be customized to reset pin, low level effective, if you need to use please contact Ai-Thinker
2	IO20	GPIO20/SPI_SS/I2S_BCLK/I2C_SCL/ADC_CH0/PWM0
3	EN/NC	Default as a chip enabled, high level is effective, with RST can not be used at the same time
4	IO30/NC	GPIO30/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/PWM0
5	IO10/29	Default as IO29, GPIO29/SPI_SCLK/I2S_FS/I2C_SDA/PWM0
6	IO0	GPIO0/SPI_SS/I2S_BCLK/I2C_SCL/ADC_CH9/PWM0
7	IO1	GPIO1/SPI_SCLK/I2S_FS/I2C_SDA/ADC_CH8/PWM0
8	VCC	3.3V power supply; the output current of external power supply is recommended to be above 500 mA
9	IO15	GPIO15/SPI_MOSI/I2S_DO/I2S_RCLK_O/I2C_SDA/PWM0

10	IO14	GPIO14/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/ADC_CH4/PWM0
11	IO11	GPIO11/SPI_MOSI/I2S_DO/I2S_RCLK_O/I2C_SDA/PWM0
12	IO12	GPIO12/SPI_SS/I2S_BCLK/I2C_SCL/ADC_CH6/PWM0
13	DP	USB_DP
14	DM	USB_DM
15	GND	Ground
16	IO13/28	Default as IO28, GPIO28/SPI_SS/I2S_BCLK/I2C_SCL/ADC_CH11/PWM0
17	IO3	GPIO3/SPI_MOSI/I2S_DO/I2S_RCLK_O/I2C_SDA/ADC_CH3/PWM0
18	IO2/NC	Default NC, if need to use IO2, please contact Ai-Thinker, support Bootstrap/GPIO2/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/ADC_CH,sh angdian2/PWM0
19	IO17	The default is available. The IO port is shared with the 32.768KHz crystal vibration output PIN pin inside the module. If the module of the internal patch 32.768KHz crystal vibration is customized, the IO is in the NC state.GPIO17/SPI_SCLK/I2S_FS/I2C_SDA/XTAL_32K_OUT/PWM0
20	IO16	The default is available. The IO port is shared with the 32.768KHz crystal vibration output PIN pin inside the module. If the module of the internal patch 32.768KHz crystal vibration is customized, the IO is in the NC state.GPIO16/SPI_SS/I2S_BCLK/I2C_SCL/XTAL_32K_OUT/PWM0
21	RXD	RXD/GPIO22/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/PWM0
22	TXD	TXD/GPIO21/SPI_SCLK/I2S_FS/I2C_SDA/ADC_RCAL_VOUT/PWM0
Test point	IO2	Bootstrap/GPIO2/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/ADC_CH,sh angdian2/PWM0
<p>Note: 1. When the measuring point IO2 is Bootstrap, the module enters the burning mode; when the power-on moment is low level, the module starts normally.</p>		

## 5. Schematic diagram

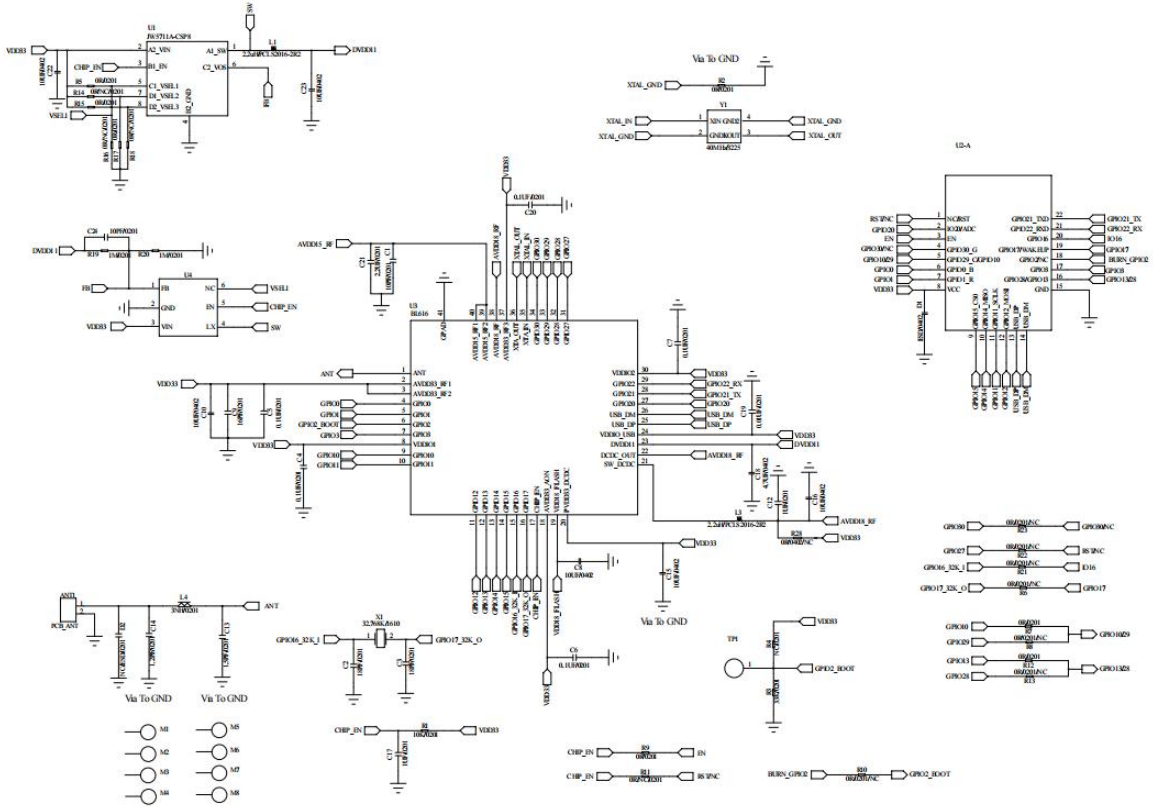


Figure 6 Schematic diagram

## 6. Design guidance

### 6.1. Guidance of application circuit

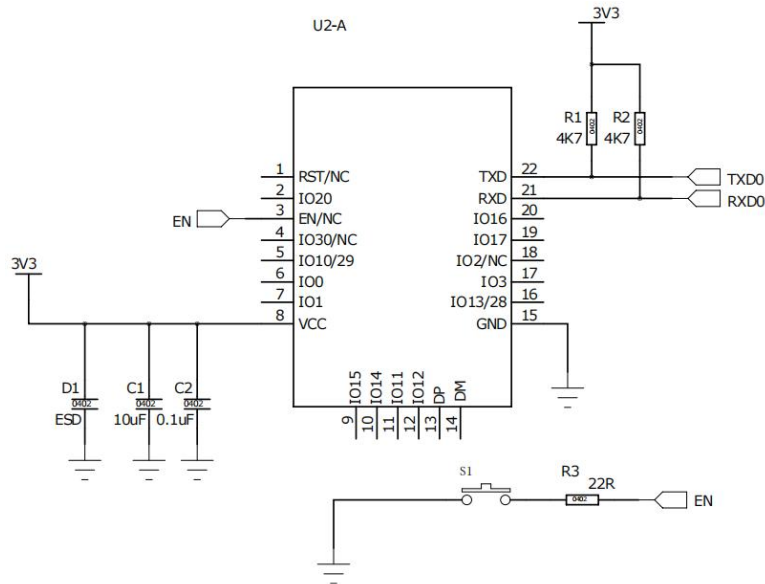


Figure 7 Guidance of application circuit

- IO16、IO17, the default is available. The IO port is shared with the 32.768KHz crystal vibration output PIN foot inside the module. If the module of the internal patch 32.768KHz crystal vibration is customized, this IO is in the NC state.

### 6.2. Recommend PCB package size

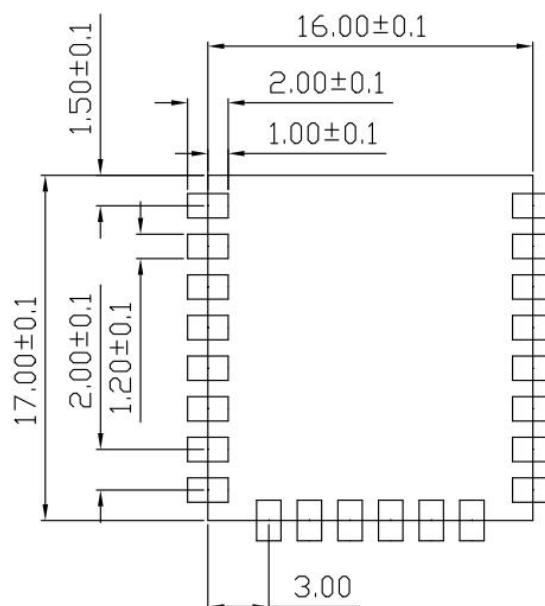


Figure 8 Recommended PCB package sizes (Unit mm)

### 6.3. Antenna layout requirements

- The module requires use with an external antenna.
- In order to satisfy the performance of the antenna, metal parts are not placed around the antenna, away from high frequency devices.

### 6.4. Power supply

- Recommended 3.3V voltage, peak current above 500 mA.
- It is recommended to use LDO; if DC-DC, ripple control within 30 mV.
- The DC-DC power supply circuit suggests to reserve the position of the dynamic response capacitor, which can optimize the output ripple when the load changes greatly.
- 3.3V power interface, it is recommended to add ESD devices.

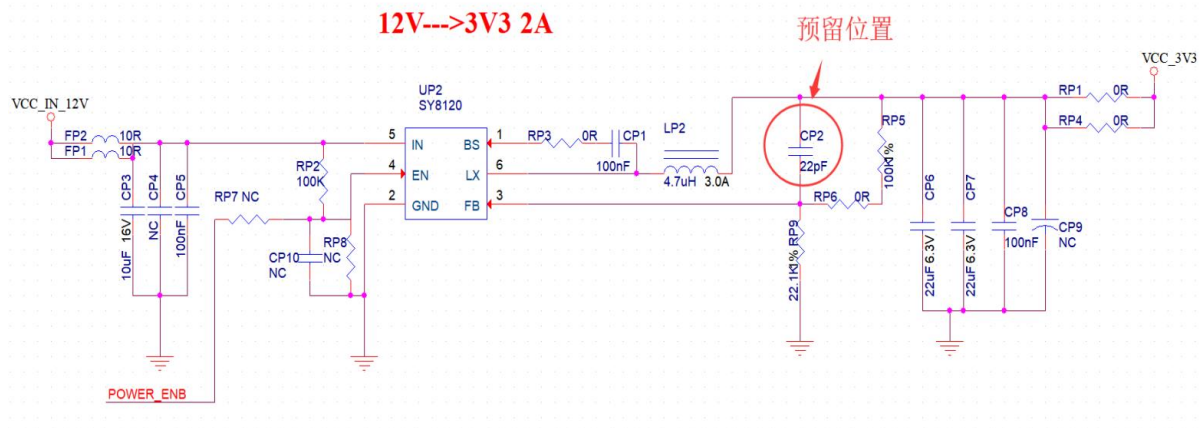
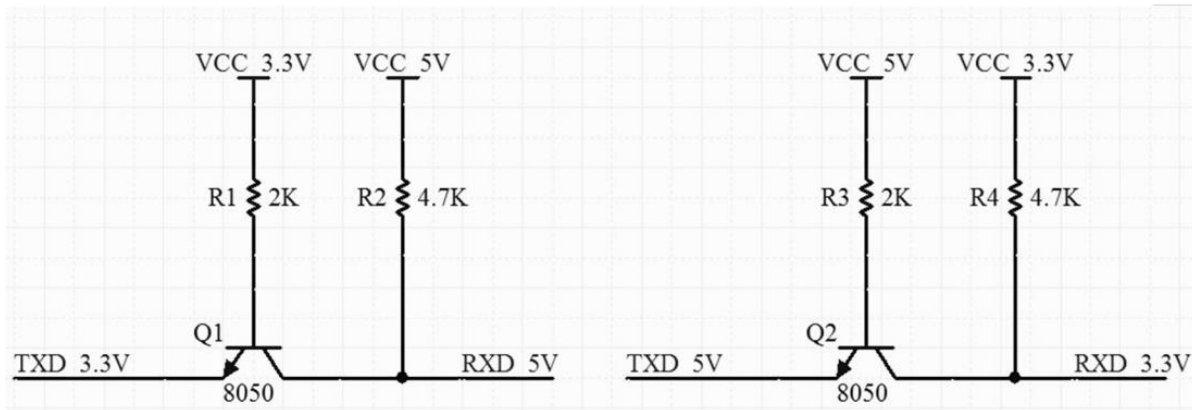


Figure 9 The DC-DC step-down circuit diagram

### 6.5. GPIO

- Outside the module are some IO ports, with a recommended resistance of 10 to 100 ohms on the IO port in series. This can suppress the overshoot and make the level on both sides more stable. For both EMI and ESD.
- Pull up and down of the special IO port, refer to the instructions of the specification, which will affect the startup configuration of the module.
- The IO port of the module is 3.3V. If the main control does not match the IO port level of the module, the level conversion circuit should be added.
- If the IO port is directly connected to the peripheral interface or terminals, it is

recommended to reserve ESD devices at the IO port line near the terminal.



**Figure 10 The level conversion circuit**

## 7. Storage condition

Products sealed in a moisture-proof bag shall be stored in a non-condensing atmosphere of  $<40^{\circ}\text{C} / 90\% \text{RH}$ .

The moisture sensitivity grade MSL of the module is level 3.

After the vacuum bag is unsealed, it must be used within 168 hours at  $25 \pm 5^{\circ}\text{C} / 60\% \text{RH}$ , otherwise it needs to be baked before the secondary production.

## 8. Reflow welding curve diagram

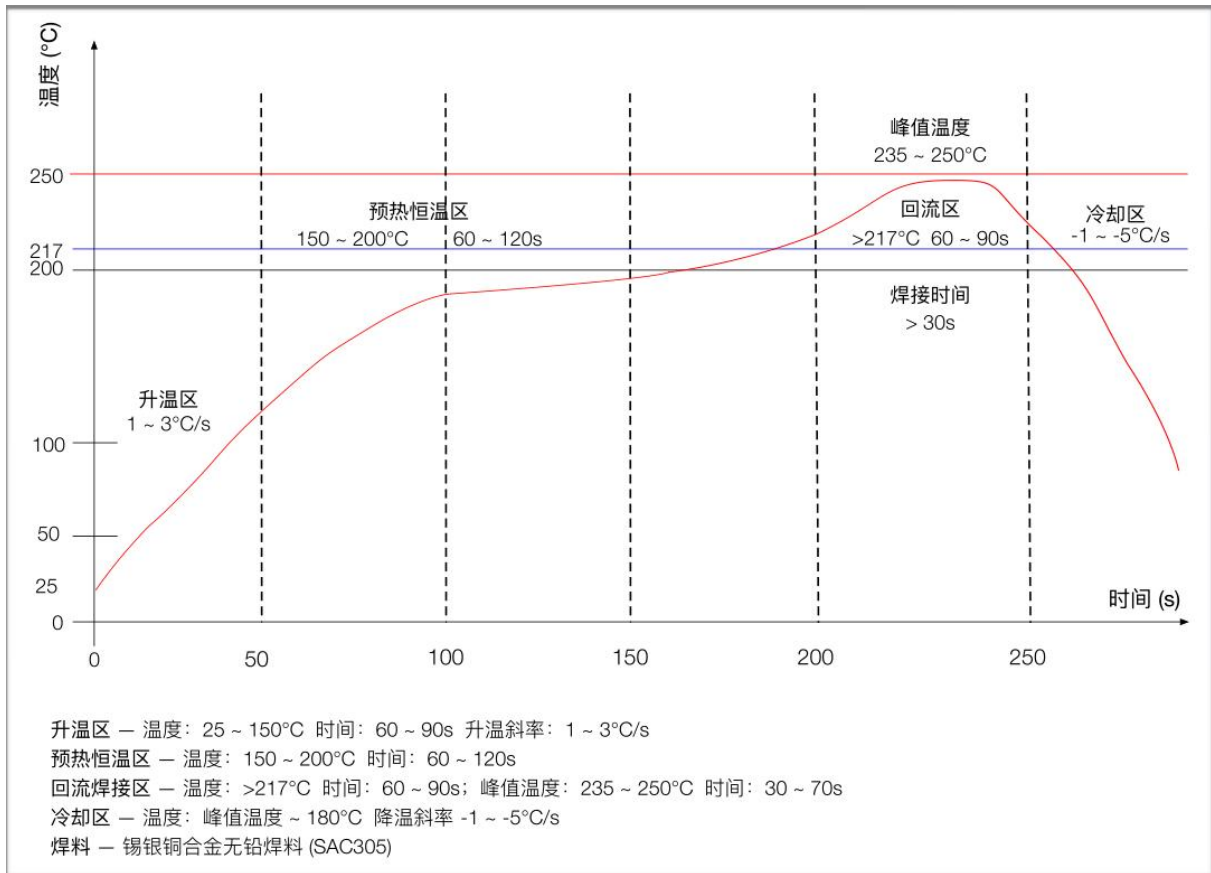


Figure 11 Reflow welding curve diagram



## 9. Product packaging information

Ai-M62-07S module is packaged with 800 pcs / reel. As shown in the figure below:



Figure 12 Reel packing diagram

## 10. Contact us

[Ai-Thinker official website](#)

[Office forum](#)

[Develop DOCS](#)

[LinkedIn](#)

[Tmall shop](#)

[Taobao shop](#)

[Alibaba shop](#)

[Technical support email: support@aithinker.com](mailto:support@aithinker.com)

[Domestic business cooperation: sales@aithinker.com](mailto:sales@aithinker.com)

[Overseas business cooperation: overseas@aithinker.com](mailto:overseas@aithinker.com)

Company Address: Room 403-405,408-410, Block C, Huafeng Smart Innovation Port, Gushu 2nd Road, Xixiang, Baoan District, Shenzhen.

Tel: +86-0755-29162996



WeChat mini program



WeChat official account

## Disclaimer and copyright notice

The information in this article, including the URL address for reference, is subject to change without notice.

The document is provided "as is" without any guarantee responsibility, including any guarantee for merchantability, suitability for a specific purpose, or non-infringement, and any guarantee mentioned elsewhere in any proposal, specification or sample. This document does not bear any responsibility, including the responsibility for infringement of any patent rights arising from the use of the information in this document. This document does not grant any license for the use of intellectual property rights in estoppel or other ways, whether express or implied.

The test data obtained in the article are all obtained from Ai-Thinker's laboratory tests, and the actual results may vary slightly.

All brand names, trademarks and registered trademarks mentioned in this article are the property of their respective owners, and it is hereby declared.

The final interpretation right belongs to Shenzhen Ai-Thinker Technology Co., Ltd.

## Notice

Due to product version upgrades or other reasons, the contents of this manual may be changed.

Shenzhen Ai-Thinker Technology Co., Ltd. reserves the right to modify the contents of this manual without any notice or prompt.

This manual is only used as a guide. Shenzhen Ai-Thinker Technology Co., Ltd. makes every effort to provide accurate information in this manual. However, Shenzhen Ai-Thinker Technology Co., Ltd. does not guarantee that the contents of the manual are completely free of errors. All statements and information in this manual And the suggestion does not constitute any express or implied guarantee.

## Important statement

Ai-Thinker may provide technical and reliability data "as is" (including data sheets), design resources (including design for reference purposes), application or other design recommendations, network tools, security information and other resources (the "these resources") and without warranty without express or implied warranty, including without limitation, adaptability for a particular purpose or infringement of intellectual property rights of any third party. And specifically declares that it is not liable for any inevitable or incidental losses arising from the application or the use of any company products and circuits.

Ai-Thinker reserves the right to the information released in this document (including but not limited to the indicators and product description) and any changes to the Company without notice to automatically replace and replace all the information provided in the previous version of the same document number document.

These resources are available to skilled developers who design Essence products. You will assume all responsibilities for the following: (1) select the appropriate optional products for your application; (2) design, verify, and run your application and products during the full life cycle; and (3) ensure that your application meets all corresponding standards, norms and laws, and any other functional.

Ai-Thinker authorizes you to use these resources only for the application of the Ai-Thinker products described in this resource. Without the permission of Ai-Thinker, no unit or individual shall copy or copy part or all of these resources without authorization, and shall not spread them in any form. You are not entitled to use any other Principal or any third party intellectual property. You shall fully indemnify you for any claims, damages, costs, losses and debts incurred by the result of the use of these resources.

The products available by Ai-Thinker are subject to the terms of sales or other applicable terms attached to the products. Ai-Thinker may provide these resources does not extend or otherwise change the applicable warranty or warranty disclaimer for the product release.